



Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 53692

Application ID: 10667227



Title of Invention: SEMICONDUCTOR PACKAGE AND  
METHOD OF MAKING  
LEADFRAME HAVING LEAD  
LOCKS TO SECURE LEADS TO  
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-09-18

Effective Receipt Date: 2004-01-14

Submission Type: Information Disclosure  
Statement

Filing Type:

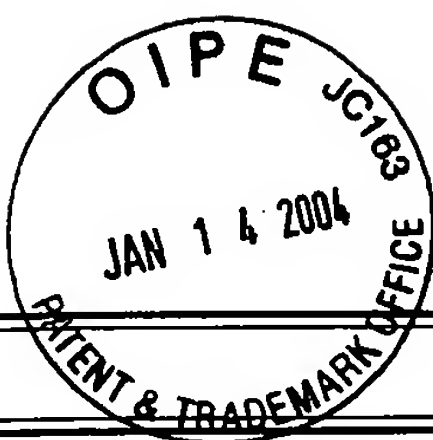
Confirmation number: 7012

Attorney Docket Number: AMKOR012G1

Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US


Certificate Message Digest: ec0661730350568f058c09c92c4ea85dbd43ffc9

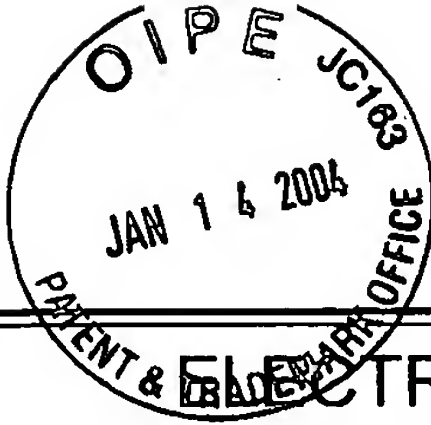


# TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT									
Application Number: 10/667227 										
Date: 2003-09-18										
First Named Applicant: Jae Hak Yee										
Confirmation Number: 7012										
Attorney Docket Number: AMKOR012G1										
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>										
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids3-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids3-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids3-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18  
Stylesheet Version v18.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT
-----------------------	---

Application Number: 10/667227  
Confirmation Number: 7012  
First Named Applicant: Jae Yee  
Attorney Docket Number: AMKOR012G1  
Art Unit: 2812  
Search string: ( 5640047 or 5639990 or 5641997 or 5644169  
or 5643433 or 5646831 or 5650663 or 5661088  
or 5665996 or 5673479 or 5683806 or 5689135  
or 5696666 or 5701034 or 5703407 or 5710064  
or 5724233 or 5723899 or 5736432 or 5745984  
or 5753977 or 5753532 or 5766972 or 5770888  
or 5776798 or 5783861 or 5801440 or 5814884  
or 5814883 or 5814881 or 5814877 or 5818105  
or 5817540 or 5821615 or 5821457 or 5835988  
or 5834830 or 5844306 or 5856911 or 5859471  
or 5866939 or 5871782 or 5874784 or 5877043  
or 5886398 or 5886397 or 5894108 or 5897339  
or 5900676 or 5903050 ).pn.



US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5640047	1997-06-17	NAKASHIMA			
	2	5639990	1997-06-17	NISHIHARA ET AL.			
	3	5641997	1997-06-24	OHTA ET AL.			
	4	5644169	1997-07-01	CHUN			
	5	5643433	1997-07-01	FUKASE ET AL.			
	6	5646831	1997-07-08	MANTEGHI			
	7	5650663	1997-07-22	PARTHASARANTHI			
	8	5661088	1997-08-26	TESSIER ET AL.			

	9	5665996	1997-09-09	WILLIAMS ET AL.
	10	5673479	1997-10-07	HAWTHORNE
	11	5683806	1997-11-04	SAKUMOTO ET AL.
	12	5689135	1997-11-18	BALL
	13	5696666	1997-12-09	MILES ET AL.
	14	5701034	1997-12-23	MARRS
	15	5703407	1997-12-30	HORI
	16	5710064	1998-01-20	SONG ET AL.
	17	5724233	1998-03-03	HONDA ET AL.
	18	5723899	1998-03-03	SHIN
	19	5736432	1998-04-07	MACKESSY
	20	5745984	1998-05-05	COLE, JR. ET AL.
	21	5753977	1998-05-19	KUSAKA ET AL.
	22	5753532	1998-05-19	SIM
	23	5766972	1998-06-16	TAKAHASHI ET AL.
	24	5770888	1998-06-23	SONG ET AL.
	25	5776798	1998-07-07	QUAN ET AL.
	26	5783861	1998-07-21	SON
	27	5801440	1998-09-01	CHU ET AL.
	28	5814884	1998-09-29	DAVIS ET AL.
	29	5814883	1998-09-29	SAWAI ET AL.
	30	5814881	1998-09-29	ALAGARATNAM ET AL.
	31	5814877	1998-09-29	DIFFENDERFER ET AL.
	32	5818105	1998-10-06	KOUDA
	33	5817540	1998-10-06	WARK
	34	5821615	1998-10-13	LEE
	35	5821457	1998-10-13	MOSLEY ET AL.
	36	5835988	1998-11-10	ISHII
	37	5834830	1998-11-10	CHO
	38	5844306	1998-12-01	FUJITA ET AL.
	39	5856911	1999-01-05	RILEY
	40	5859471	1999-01-12	KURAISHI ET AL.
	41	5866939	1999-02-02	SHIN ET AL.
	42	5871782	1999-02-16	CHOI
	43	5874784	1999-02-23	AOKI ET AL.
	44	5877043	1999-03-02	ALCOE ET AL.

	45	5886398	1999-03-23	LOW ET AL.
	46	5886397	1999-03-23	EWER
	47	5894108	1999-04-13	MOSTAFAZADEH ET AL.
	48	5897339	1999-04-27	SONG ET AL.
	49	5900676	1999-05-04	KWEON ET AL.
	50	5903050	1999-05-11	THURAIRAJARATNAM ET AL.

Signature

Examiner Name	Date